In the Claims:

Please amend claims 23, 29, and 30. The claims are as follows:

1. (Withdrawn) A method for making a conductive path in a laminate structure hole comprising the steps of:

providing a laminate with a top surface and a bottom surface and having at least one hole;

providing a conductive element;

inserting the conductive element into the at least one hole in the laminate; and

deforming the conductive element within the at least one hole in the laminate to retain the conductive element within the at least one hole.

2. (Withdrawn) The method of claim 1, wherein the deforming of the conductive element further includes forming an electrode at the top surface of the laminate.

3. (Withdrawn) The method of claim 1, wherein the at least one hole is a through hole extending from the top surface to the lower surface of the laminate.

4. (Withdrawn) The method of claim 1, wherein the conductive element is a sphere.

5. (Withdrawn) The method of claim 4, wherein the sphere is solid or hollow.

6. (Withdrawn) The method of claim 1, wherein the at least one hole is a blind via.

7. (Withdrawn) The method of claim 1, wherein the conductive element includes a conductive surface covering a base element.

8. (Withdrawn) The method of claim 7, wherein the conductive surface is selected from the group consisting of copper, brass, gold, and bronze.

9. (Withdrawn) The method of claim 7, wherein the base element is selected from the group consisting of glass, rubber, and plastic.

10. (Withdrawn) The method of claim 1, wherein the conductive element is a cylinder.

11. (Withdrawn) The method of claim 10, wherein the cylinder is solid or hollow.

12.(Withdrawn) The method of claim 1, wherein the conductive element is selected from the group consisting of copper, brass, gold, and bronze.

13. (Withdrawn) The method of claim 1, wherein the at least one hole is a buried via.

14.(Withdrawn) A method comprising:

embedding a conductive element into a laminate, wherein the conductive element substantially maintains a shape while the laminate deforms to accommodate the conductive element.

15. (Withdrawn) The method of claim 14, wherein the conductive element includes a conductive surface covering a base element.

16. (Withdrawn) The method of claim 15, wherein the conductive surface is selected from the group consisting of copper, brass, gold, and bronze.

17. (Withdrawn) The method of claim 15, wherein the base element is selected from the group consisting of glass, rubber, and plastic.

18. (Withdrawn) The method of claim 15, wherein the conductive element is selected from the group consisting of copper, brass, gold, and bronze.

19. (Withdrawn) The method of claim 15, wherein the conductive element is a sphere or a cylinder.

20. (Withdrawn) The method of claim 15, wherein the conductive element is hollow.

21. (Previously presented) A method of forming a conductive path within a laminate, comprising:

providing an opening in the laminate;

pressing a conductive element into the opening such that a portion of at least one end of the conductive element extends beyond a surface of the laminate; and

applying a compressive pressure to the portion of the at least one end of the conductive

element, wherein the compressive pressure applied to the portion of the at least one end of the conductive element forms a contact pad extending beyond the surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element.

22. (Original) The method of claim 21, wherein the opening is a hole.

23. (Currently amended) ~~The method of claim 21~~ A method of forming a conductive path within a laminate, comprising:

providing an opening in the laminate;

pressing a conductive element into the opening such that a portion of at least one end of the conductive element extends beyond a surface of the laminate; and

applying a compressive pressure to the portion of the at least one end of the conductive element, wherein the compressive pressure applied to the portion of the at least one end of the conductive element forms a contact pad extending beyond the surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element, wherein the conductive element is a sphere.

24. (Original) The method of claim 21, wherein the conductive element is a cylinder.

25.(Withdrawn) A method comprising:

providing a plurality of laminates;

embedding at least one conductive element into each laminate;

forming a contact pad on each end of each conductive element;

bonding each laminate together to form a stack; and

wherein adjoining contact pads press together and form an electrical connection.

26.(Withdrawn) The method of claim 25, further including a conductive adhesive applied between adjoining contact pads.

27. (Previously presented) A structure for interconnection between circuit layers, comprising:

a laminate having a conductive inner plane;

a conductive pad on a surface of the laminate, wherein a bottom surface of the conductive pad is in direct mechanical contact with the surface of the laminate;

a conductive element having a lower portion and an upper portion, wherein the lower portion of the conductive element is embedded into the laminate, wherein the upper portion of the conductive element extends above the surface of the laminate, wherein the conductive pad circumscribes the upper portion of the conductive element, wherein the conductive element electrically connects the conductive inner plane to the surface of the laminate, wherein the lower portion of the conductive element comprises a conductive material, and wherein the upper portion of the conductive element comprises the conductive material.

28. (Previously presented) The structure of claim 27, further including an opening in the laminate that the conductive element is pressed into.

29. (Currently amended) ~~The structure of claim 27~~ A structure for interconnection between circuit layers, comprising:

a laminate having a conductive inner plane;

a conductive pad on a surface of the laminate, wherein a bottom surface of the conductive pad is in direct mechanical contact with the surface of the laminate;

a conductive element having a lower portion and an upper portion, wherein the lower portion of the conductive element is embedded into the laminate, wherein the upper portion of the conductive element extends above the surface of the laminate, wherein the conductive pad circumscribes the upper portion of the conductive element, wherein the conductive element electrically connects the conductive inner plane to the surface of the laminate, wherein the lower portion of the conductive element comprises a conductive material, and wherein the upper portion of the conductive element comprises the conductive material, wherein a top surface of the conductive pad is coplanar with a top surface of the upper portion of the conductive element.

30. (Currently amended) ~~The structure of claim 27~~ A structure for interconnection between circuit layers, comprising:

a laminate having a conductive inner plane;

a conductive pad on a surface of the laminate, wherein a bottom surface of the conductive pad is in direct mechanical contact with the surface of the laminate;

a conductive element having a lower portion and an upper portion, wherein the lower portion of the conductive element is embedded into the laminate, wherein the upper portion of the conductive element extends above the surface of the laminate, wherein the conductive pad

circumscribes the upper portion of the conductive element, wherein the conductive element electrically connects the conductive inner plane to the surface of the laminate, wherein the lower portion of the conductive element comprises a conductive material, and wherein the upper portion of the conductive element comprises the conductive material, wherein part of the upper portion of the conductive element extends above the conductive pad.

31. (Previously presented) The structure of claim 27, wherein the conductive material is selected from the group consisting of: gold, copper, brass, and bronze.

32. (Previously presented) The structure of claim 30, wherein the part of the upper portion of the conductive element that extends above the conductive pad is on, and in direct mechanical contact with, a top surface of the conductive pad.

33-34. (Canceled)

35. (Previously presented) The structure of claim 30, wherein the part of the upper portion of the conductive element that extends above the conductive pad is not on a top surface of the conductive pad.

36. (Previously presented) A method of forming a conductive path within a laminate, comprising:

providing an opening in the laminate;

pressing a conductive element into the opening such that a portion of at least one end of the conductive element extends beyond a surface of the laminate; and

applying a compressive pressure to the portion of the at least one end of the conductive element, wherein the compressive pressure applied to the portion of the at least one end of the conductive element forms a contact pad extending beyond a surface of the laminate.

37. (Previously presented) A structure for interconnection between circuit layers, comprising:

a first laminate having a first conductive element embedded into the first laminate wherein a portion of the first conductive element forms at least one contact pad extending beyond a surface of the first laminate;

a second laminate having a second conductive element embedded into the second laminate wherein a portion of the second conductive element forms at least one contact pad extending beyond a surface of the second laminate; and

a bonding layer between the first and second laminates such that the contact pads of the first and second conductive elements are electrically connected, wherein the bonding layer comprises conductive metal filled epoxy.

38. (Previously presented) A method of forming a conductive path within a laminate, comprising the steps of:

providing a conductive element;

projecting the conductive element toward a surface of the laminate;

impacting the surface of the laminate by the conductive element, wherein said impacting

forms a hole in the laminate such that the entire conductive element provided in the providing step becomes embedded within the hole.

39. (Previously presented) The method of claim 38, wherein the conductive element is a sphere.

40. (Canceled)